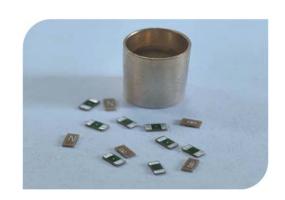


#### 0402FA-L Series

# Ultra-Thin Fuse | 0.04x0.02" Fast Acting series Thin Film Chip Fuse

#### **Features**

- Very fast acting at 200% overload current
- Low DCR
- High inrush current withstanding capability
- High reliability
- Fiberglass enforced epoxy fuse body
- Copper termination with nickel and tin plating layer
- Halogen free, RoHS compliance & lead-free



#### **Application**

Battery pack

●HDD

Finger print

Toy

● Smart lock

● loT

Notebook

#### **Electrical Characteristics**

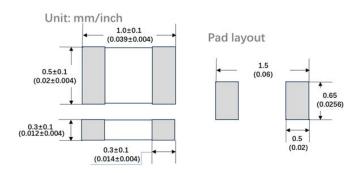
% of Current Rating	Opening Time	
100%	4hours min.	
200%	5second max.	
300%	0.2second max.	

### **Specifications**

Part No.	Current Rating(A)	Voltage Rating (Vdc)	Interrupting Rating	Typical Cold DCR (Ω)	Typical l <sup>2</sup> t (A <sup>2</sup> Sec)*	Marking
0402FA-R500-L	0.5	35	35A @35V	0.165	0.007	=

<sup>\*</sup>Typical I2t: i.e. melting I2t at 0.001s of current rating

### **Dimension**



#### **Packaging**

- Quantity:10, 000pcs
- 8mm wide tape on 178mm (7 inch) diameter reel -specification EIA Standard 481

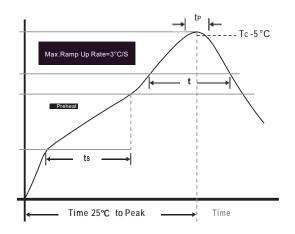


# 0402FA-L Series

# Ultra-Thin Fuse | 0.04x0.02"

# Fast Acting series Thin Film Chip Fuse

# **Soldering Parameters**



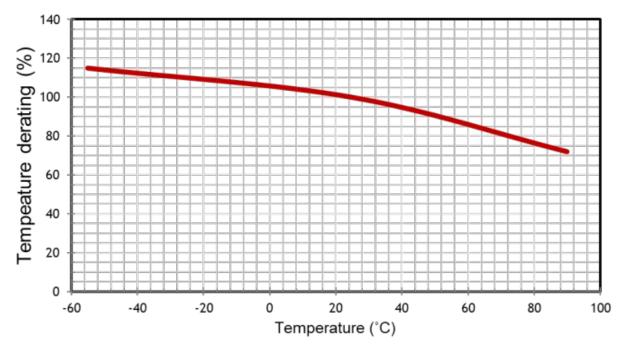
Wave Soldering: 260°C, 10 seconds max.

Infrared Reflow: 260°C, 30 seconds max.

**IR Reflow Profile** 

Preheat Heat Temperature min (Tsmin) Temperature max(Tsmax) Time (Tsmin to Tsmax) (ts)	150°C 200°C 60 -120 seconds
Average ramp-up rate (Tsmax to Tp)	3°C/second max.
Liquidous temperature (TL) Time at liquidous (tL)	217 °C 60 - 150 seconds
Peak temperature(Tp)	260°C
Time within 5°C of actual peak Temperature (tp)	30 seconds
Average ramp-down rate (Tp to Tsmax)	6°C/second max.
Time 25 °C to peak temperature	8 minutes max.

# **Temperature Effect on Current Rating**



Normal ambient temperature: 23+/-3℃

Operating temperature: -55 ~ 105°C



# Ultra-Thin Fuse | 0.04x0.02" Fast Acting series Thin Film Chip Fuse

# **Average Time-Current curve**

